

RELIABILITY MONITOR

PRODUCT	MONITOR DATE	DATE CODE	ASSEMBLY FACILITY	ASSEMBLY LOT NO	PROCESS TYPE	PACKAGE TYPE
DS12887 (w/BR1225)	Jan-97	9650 A2	DALLAS	DA089784	N/A	24 MODULE

STRESS/JOB NO.

**READPOINT
(Sample Size/No. of Fails)**

Hi Temp Storage
85°C, No Bias
P-18895

48 Hr
200/0

Cum %
0.0%

Temp Cycle
0°C to +70°C
P-18922

300 ~ 1K ~
100/0

Cum %

Biased Moisture
85°C/85% RH, 5.5 V.
P-18923

274 Hr 959 Hr
100/0 100/1
F1

Cum %
1.0%

Phys. Dimen.
P-18894

Solderability
P-18893

Failure Mode

F1: Functional

Failure Analysis

In process, 970059